

### Main Product Characteristics:

**Features and Benefits** 

# **Description:**

# **Absolute Max Rating:**

Symbol	Parameter	Max.	Units
$I_D @ T_C = 25^{\circ}C$	Continuous Drain Current, V <sub>GS</sub> @ 10V	-3.5	A
I <sub>DM</sub>	Pulsed Drain Current	-14	
	•	·	

 $P_D @T_C = 25^{\circ}C$ 



### **Thermal Resistance**

Symbol

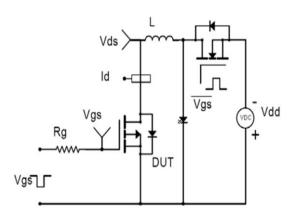
Characterizes

Typ. M(pen5E(

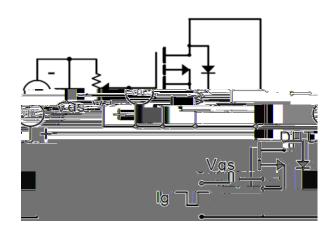


## **Test Circuits and Waveforms**

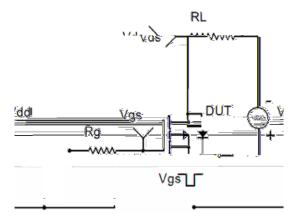
#### EAS Test Circuit:



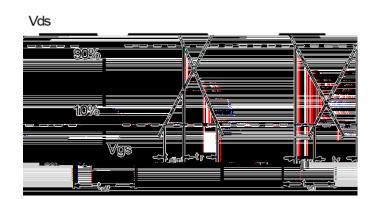
Gate Charge Test Circuit:



Switching Time Test Circuit:



Switching Waveforms:



#### Notes:

Calculated continuous current based on maximum allowable junction temperature.

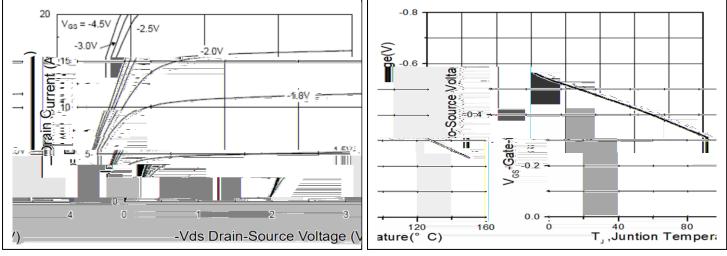
Repetitive rating; pulse width limited by max. junction temperature.

The power dissipation  $P_D$  is based on max. junction temperature, using junction-to-case thermal resistance.

The value of R  $_A$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25°C



# SSF1341UP



# **Typical Electrical and Thermal Characteristics**

**Figure1.Typical Output Characteristics** 

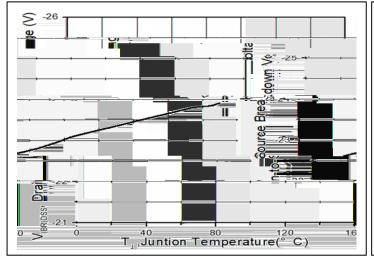


Figure3. Drain-to-Source Breakdown Voltage vs. Junction Temperature

-4.50

-3.75

ain Current (A)

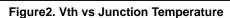
100

erature-(-C-)-

ð 1.50

140

120



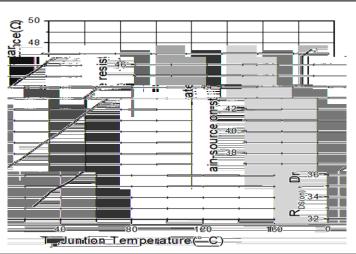


Figure4. R<sub>DS(on)</sub> vs. Junction Temperature

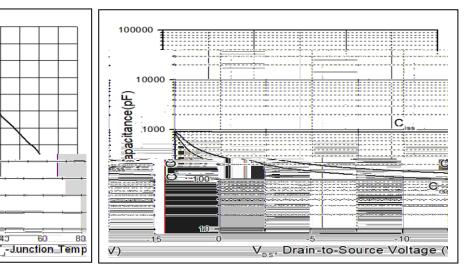


Figure5. Drain Current vs. Junction Temperature

Figure6. Capacitance

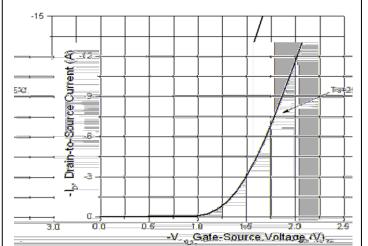
0.75

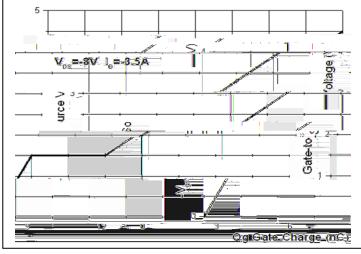
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60



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# **Typical Electrical and Thermal Characteristics**

Figure7. Transfer Characteristics

Figure8. Gate source voltage vs. Gate Charge

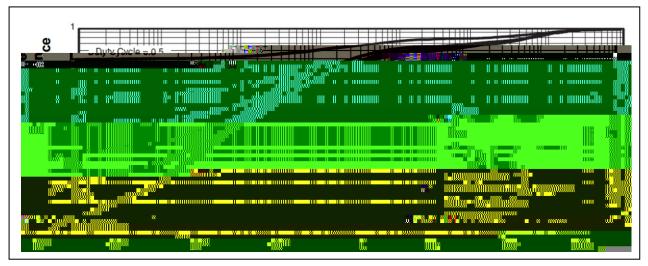
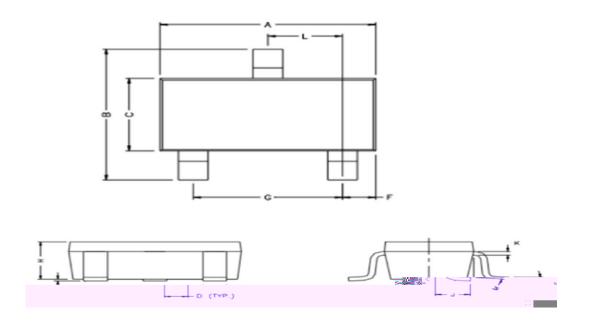


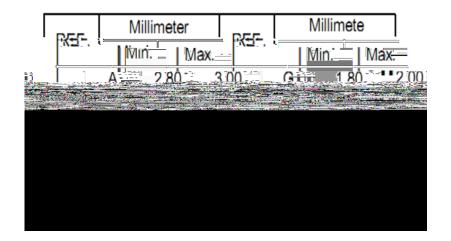
Figure9. Normalized Maximum Transient Thermal Impedance



### **Mechanical Data**

#### SOT-23 Package Outline(Unit:mm)







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